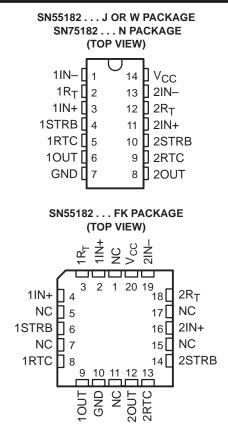
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- Single 5-V Supply
- Differential Line Operation
- Dual Channels
- TTL Compatibility
- ±15-V Common-Mode Input Voltage Range
- ±15-V Differential Input Voltage Range
- Individual Channel Strobes
- Built-In Optional Line-Termination Resistor
- Individual Frequency Response Controls
- Designed for Use With Dual Differential Drivers SN55183 and SN75183
- Designed to Be Interchangeable With National Semiconductor DS7820A and DS8820A

#### description

The SN55182 and SN75182 dual differential line receivers are designed to sense small differential signals in the presence of large common-mode noise. These devices give TTL-compatible output signals as a function of the polarity of the differential input voltage. The frequency response of each channel can be easily controlled by a single external capacitor to provide immunity to differential noise spikes. The output goes to a high level when the inputs are open circuited. A strobe input (STRB) is provided that, when in the low level, disables the receiver and forces the output to a high level.



NC - No internal connection

#### THE SN55182 IS NOT RECOMMENDED FOR NEW DESIGNS

The receiver is of monolithic single-chip construction, and both halves of the dual circuits use common power-supply and ground terminals.

The SN55182 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN75182 is characterized for operation from 0°C to 70°C.

INPU	INPUTS							
STRB	VID	OUT						
L	Х	Н						
н	Н	Н						
н	L	L						
$H = V_1 > V_{111}$ min or $V_{122}$ more								

#### FUNCTION TABLE



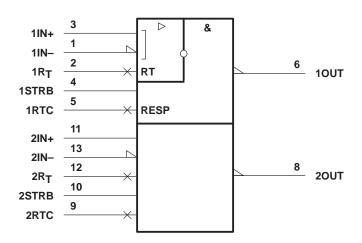
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



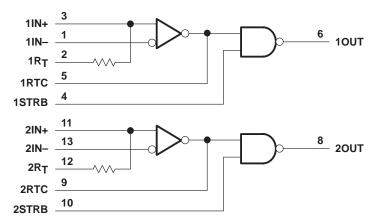
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### logic symbol<sup>†</sup>



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the J, N, and W packages.

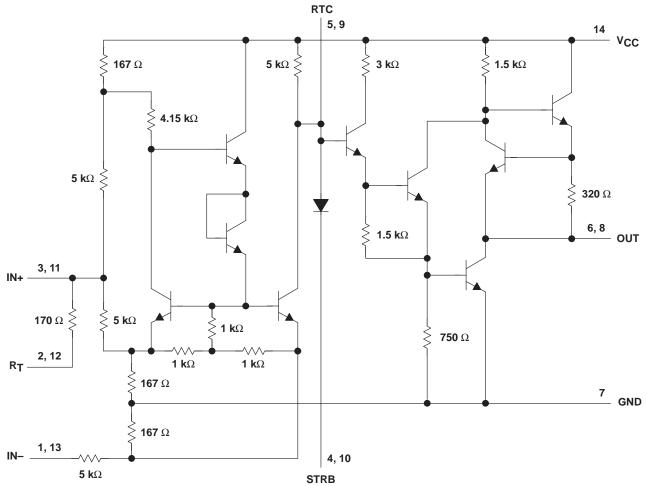
### logic diagram (positive logic)



Pin numbers shown are for the J, N, and W packages.



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Resistor values shown are nominal.

schematic (each receiver)

Pin numbers shown are for the J, N, and W packages.



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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to network ground terminal.

2. Differential voltage values are at the noninverting terminal with respect to the inverting terminal.

DISSIFATION RATING TABLE										
PACKAGE	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING						
FK‡	1375 mW	11.0 mW/°C	880 mW	275 mW						
J‡	1375 mW	11.0 mW/°C	880 mW	275 mW						
N	1150 mW	9.2 mW/°C	736 mW	-						
w‡	1000 mW	8.0 mW/°C	640 mW	200 mW						

#### DISSIPATION RATING TABLE

<sup>‡</sup> In the FK, J, and W packages, SN55182 chips are alloy mounted.

#### recommended operating conditions

	SN55182			5	UNIT		
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.5	5	5.5	4.5	5	5.5	V
Common-mode input voltage, V <sub>IC</sub>			±15			±15	V
High-level strobe input voltage, VIH(STRB)	2.1		5.5	2.1		5.5	V
Low-level strobe input voltage, VIL(STRB)	0		0.9	0		0.9	V
High-level output current, IOH			-400			-400	μA
Low-level output current, IOL			16			16	mA
Operating free-air temperature, TA	-55		125	0		70	°C



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### electrical characteristics over recommended ranges of V<sub>CC</sub>, V<sub>IC</sub>, and operating free-air temperature (unless otherwise noted)

	PARAMETEI	२	TEST CONDITIONS <sup>†</sup>			түр‡	MAX	UNIT	
		ut the second state second	$V_{O} = 2.5 V$ , $V_{IC} = -3 V \text{ to } 3 V$				0.5	V	
VIT+	Positive-going inpl	ut threshold voltage	I <sub>OH</sub> = -400 μA	$V_{IC} = -15 \text{ V to } 15 \text{ V}$			1	V	
\/		wit throok old voltogo	$V_{O} = 0.4 V_{,}$	$V_{IC} = -3 V \text{ to } 3 V$			-0.5	v	
VIT-	negative-going inp	out threshold voltage	I <sub>OL</sub> = 16 mA	$V_{IC} = -15 \text{ V} \text{ to } 15 \text{ V}$			-1	V	
Veri	High-level output v	voltago	V <sub>ID</sub> = 1 V, V <sub>(STRE</sub>	B) = 2.1 V, I <sub>OH</sub> = -400 μA	2.5	4.2	5.5	V	
VOH	Figh-level output v	onage	$V_{ID} = -1 V, V_{(STR})$	RB) = 0.4 V, IOH = -400 μA	2.5	4.2	5.5	v	
VOL	Low-level output v	oltage	$V_{ID} = -1 V, V_{(STR})$	RB) = 2.1 V, IOL = 16 mA		0.25	0.4	V	
			V <sub>IC</sub> = 15 V			3	4.2		
łı	Input current	Inverting input	$V_{IC} = 0$		0	-0.5			
			V <sub>IC</sub> = -15 V		-3	-4.2	-4.2 7 mA		
			V <sub>IC</sub> = 15 V		5	7			
		Noninverting input	VIC = 0		-1	-1.4			
			V <sub>IC</sub> = -15 V		-7	-9.8			
IIH(STRB)	High-level strobe i	nput current	V <sub>(STRB)</sub> = 5.5 V				5	μΑ	
IIL(STRB)	Low-level strobe in	nput current	V(STRB) = 0			-1	-1.4	mA	
r.	Input resistance	Inverting input			3.6	5		kΩ	
rj	Input resistance	Noninverting input			1.8	2.5		K22	
	Line-terminating re	esistance	$T_A = 25^{\circ}C$	$T_A = 25^{\circ}C$		170	250	Ω	
IOS	Short-circuit outpu	t current	V <sub>CC</sub> = 5.5 V,	-2.8	-4.5	-6.7	mA		
			V <sub>IC</sub> = 15 V,	$V_{ID} = -1 V$		4.2	6		
ICC	Supply current (av	Supply current (average per receiver)		$V_{ID} = -0.5 V$		6.8	10.2	mA	
			V <sub>IC</sub> = -15 V,	$V_{ID} = -1 V$		9.4	14		

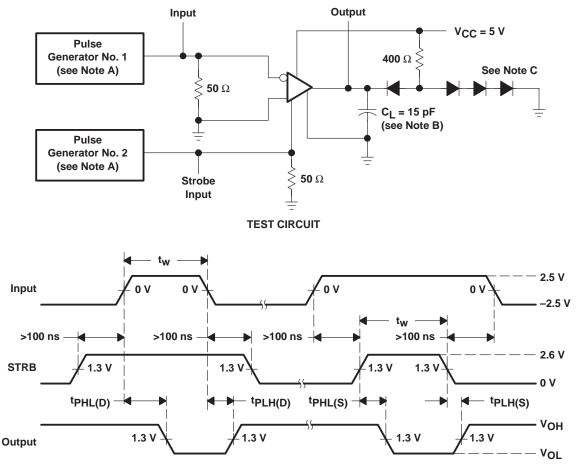
<sup>†</sup> Unless otherwise noted,  $V_{(STRB)} \ge 2.1$  V or open. <sup>‡</sup> All typical values are at  $V_{CC} = 5$  V,  $V_{IC} = 0$ , and  $T_A = 25^{\circ}C$ .

### switching characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

	PARAMETER	TE	ST CONDITIC	MIN	TYP	MAX	UNIT	
<sup>t</sup> PLH(D)	Propagation delay time, low- to high-level output from differential input	R <sub>L</sub> = 400 Ω,	C <sub>L</sub> = 15 pF,	see Figure 1		18	40	ns
<sup>t</sup> PHL(D)	Propagation delay time, high- to low-level output from differential input	R <sub>L</sub> = 400 Ω,	C <sub>L</sub> = 15 pF,	see Figure 1		31	45	ns
<sup>t</sup> PLH(S)	Propagation delay time, low- to high-level output from STRB input	RL = 400 Ω,	C <sub>L</sub> = 15 pF,	see Figure 1		9	30	ns
<sup>t</sup> PHL(S)	Propagation delay time, high- to low-level output from STRB input	R <sub>L</sub> = 400 Ω,	C <sub>L</sub> = 15 pF,	see Figure 1		15	25	ns



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#### PARAMETER MEASUREMENT INFORMATION

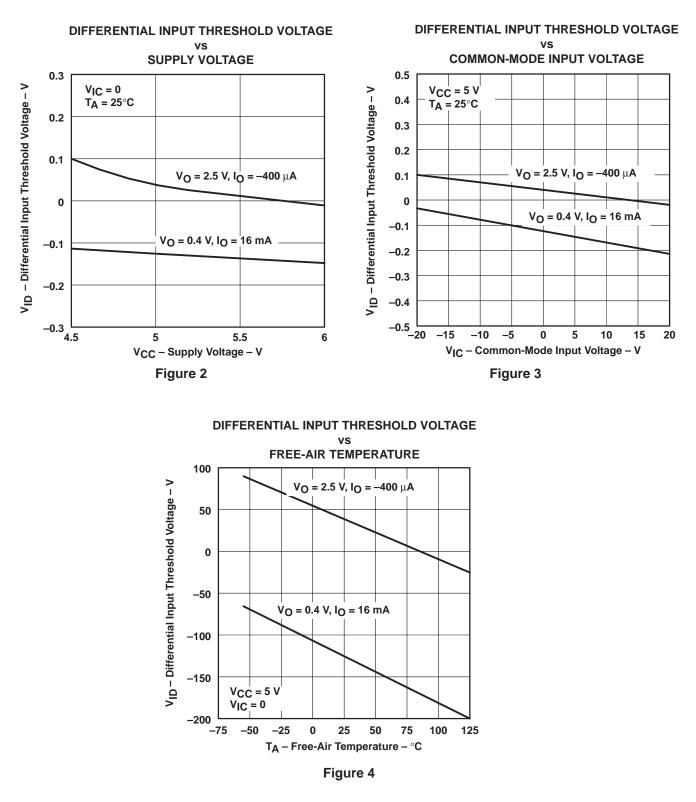
**VOLTAGE WAVEFORMS** 

- NOTES: A. The pulse generators have the following characteristics:  $Z_O = 50 \ \Omega$ ,  $t_f \le 10 \ ns$ ,  $t_f \le 10 \ ns$ ,  $t_W = 0.5 \pm 0.1 \ \mu s$ , PRR  $\le 1 \ MHz$ . B. CL includes probe and jig capacitance.
  - C. All diodes are 1N3064 or equivalent.

#### Figure 1. Test Circuit and Voltage Waveforms



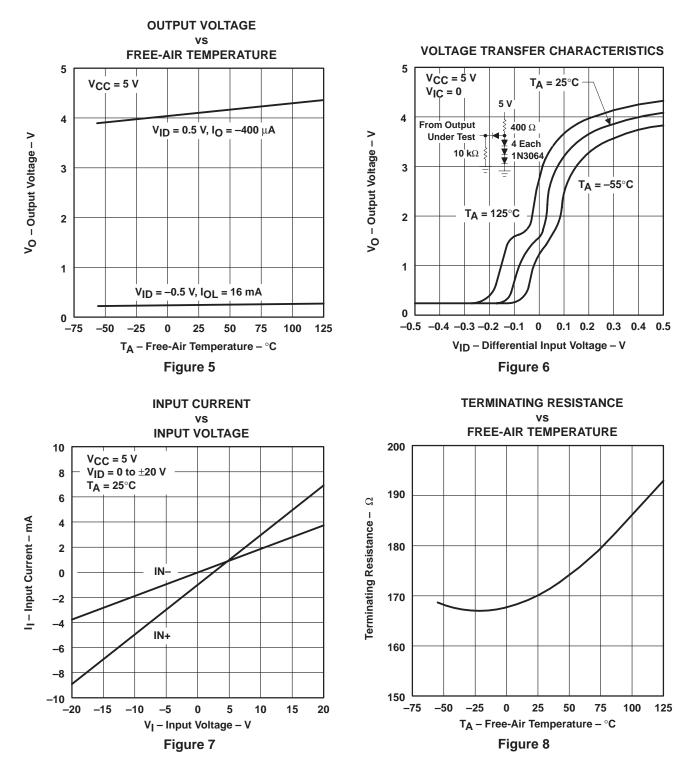
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#### **TYPICAL CHARACTERISTICS<sup>†</sup>**



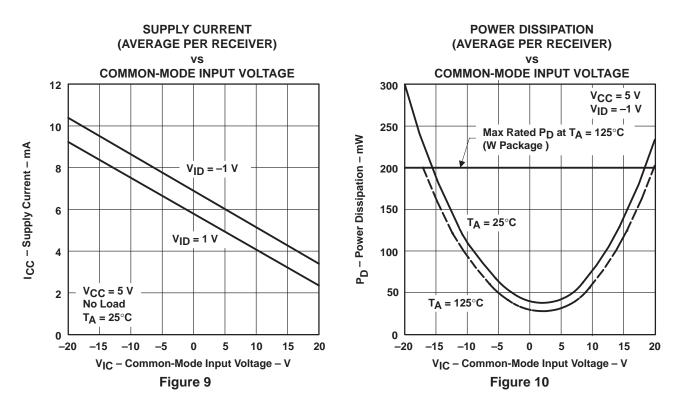
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**TYPICAL CHARACTERISTICS<sup>†</sup>** 



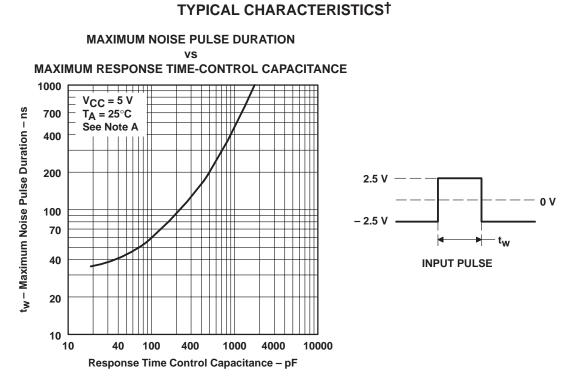
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#### **TYPICAL CHARACTERISTICS<sup>†</sup>**



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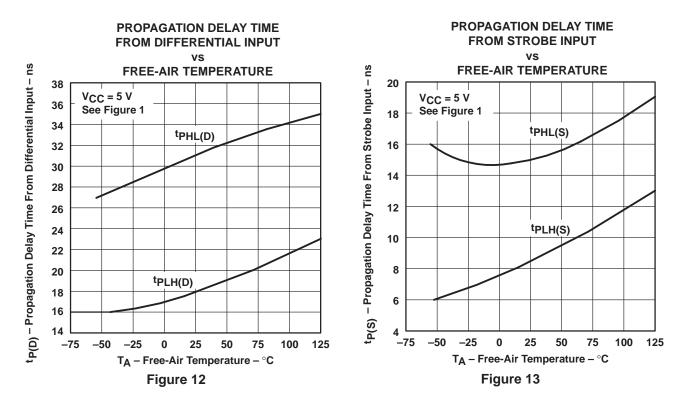


# NOTE A: Figure 11 shows the maximum duration of the illustrated pulse that can be applied differently without the output changing from the low to high level.

Figure 11



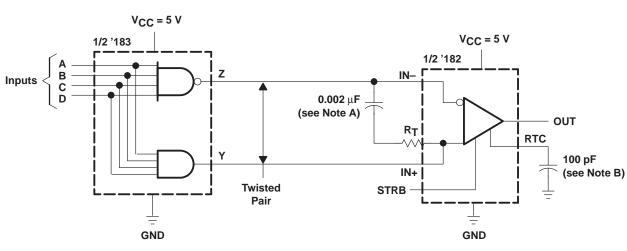
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### **TYPICAL CHARACTERISTICS<sup>†</sup>**



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### **APPLICATION INFORMATION**

NOTES: A. When the inputs are open circuited, the output is high. A capacitor may be used for dc isolation of the line-terminating resistor. At the frequency of operation, the impedance of the capacitor should be relatively small.

$$\begin{split} \text{Example: let} & \text{f} = 5 \text{ MHz} \\ & \text{C} = 0.002 \text{ } \mu\text{F} \\ \text{Z}_{(\text{C})} &= \frac{1}{2\pi\text{fC}} = \frac{1}{2\pi(5\times10^6)(0.002\times10^{-6})} \\ \text{Z}_{(\text{C})} &\approx 16\Omega \end{split}$$

B. Use of a capacitor to control response time is optional.

#### Figure 14. Transmission of Digital Data Over Twisted-Pair Line



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### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-7900801VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-7900801VDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN55182J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN75182D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75182NE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75182NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75182NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ55182FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ55182J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SNJ55182W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

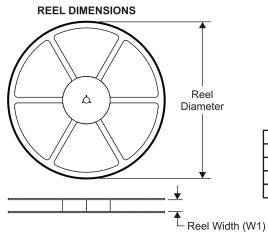


# PACKAGE OPTION ADDENDUM

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### TAPE AND REEL INFORMATION





### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*A	l dimensions are nominal												
	Device	•	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN75182DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN75182NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75182DR	SOIC	D	14	2500	346.0	346.0	33.0
SN75182NSR	SO	NS	14	2000	346.0	346.0	33.0

J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

### MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MLCC006B - OCTOBER 1996

### FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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